L Number	Hits	Search Text	DB	Time stamp
1	217	(Munakata.in. or (Shin adj Etsu).as.) and ((coat\$3 or surfactant or dip or dipped or dipping or immers\$4 or submer\$5 or deposit\$3 or film or layer) with ((wafer or chip or substrate or disc or disk) near3 (storage or storing or case or box or holder or holding or housing or carrier)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/12 15:01
2	190	(Munakata.in. or (Shin adj Etsu).as.) and ((coat\$3 or surfactant or dip or dipped or dipping or immers\$4 or submer\$5 or deposit\$3 or film or layer) with ((wafer or chip or substrate or disc or disk) near3 (storage or storing or case or box or holding or housing or carrier)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/12 15:01
3	2	(Munakata.in. or (Shin adj Etsu).as.) and ((coat\$3 or dip or dipped or dipping or immers\$4 or submer\$5 or deposit\$3 or film or layer) with ((wafer or chip or substrate or disc or disk) near3 (storage or storing or case or box or holding or housing or carrier)) with surfactant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/12 15:01
4	41	(Munakata.in. or (Shin adj Etsu).as.) and ((coat\$3 or surfactant or dip or dipped or dipping or immers\$4 or submer\$5 or deposit\$3 or film or layer) with ((wafer or chip or substrate or disc or disk) near3 (storage or storing or case or box or holding or housing or carrier))) same (dust\$3 or particle or particulate or contamin\$8)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/12 15:02
5	39	((Munakata.in. or (Shin adj Etsu).as.) and ((coat\$3 or surfactant or dip or dipped or dipping or immers\$4 or submer\$5 or deposit\$3 or film or layer) with ((wafer or chip or substrate or disc or disk) near3 (storage or storing or case or box or holding or housing or carrier))) same (dust\$3 or particle or particulate or contamin\$8)) not ((Munakata.in. or (Shin adj Etsu).as.) and ((coat\$3 or dip or dipped or dipping or immers\$4 or submer\$5 or deposit\$3 or film or layer) with ((wafer or chip or substrate or disc or disk) near3 (storage or storing or case or box or holding or housing or carrier)) with surfactant))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/12 15:02
6	149	((Munakata.in. or (Shin adj Etsu).as.) and ((coat\$3 or surfactant or dip or dipped or dipping or immers\$4 or submer\$5 or deposit\$3 or film or layer) with ((wafer or chip or substrate or disc or disk) near3 (storage or storing or case or box or holding or housing or carrier)))) not ((Munakata.in. or (Shin adj Etsu).as.) and ((coat\$3 or surfactant or dip or dipped or dipping or immers\$4 or submer\$5 or deposit\$3 or film or layer) with ((wafer or chip or substrate or disc or disk) near3 (storage or storing or case or box or holding or housing or carrier))) same (dust\$3 or particle or particulate or contamin\$8))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/12 15:03

			·	1 0 0 0 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1
7	9	((Munakata.in. or (Shin adj Etsu).as.) and ((coat\$3 or surfactant or dip or dipped or	USPAT; US-PGPUB;	2004/07/12 15:04
		dipping or immers\$4 or submer\$5 or	EPO; JPO;	
İ		deposit\$3 or film or layer) with ((wafer	DERWENT;	
		or chip or substrate or disc or disk) near3 (cassette))) ) not (((Munakata.in.	IBM_TDB	
		or (Shin adj Etsu).as.) and ((coat\$3 or		
		surfactant or dip or dipped or dipping or		
	1	immers\$4 or submer\$5 or deposit\$3 or film		
		or layer) with ((wafer or chip or		
	İ	substrate or disc or disk) near3 (storage		
		or storing or case or box or holding or housing or carrier))) ) not ((Munakata.in.		
		or (Shin adj Etsu).as.) and ((coat\$3 or		
		surfactant or dip or dipped or dipping or		
		immers\$4 or submer\$5 or deposit\$3 or film		
		or layer) with ((wafer or chip or		
		substrate or disc or disk) near3 (storage		
		or storing or case or box or holding or housing or carrier))) same (dust\$3 or		
		particle or particulate or contamin\$8)))		
8	19	(Munakata.in. or (Shin adj Etsu).as.) and	USPAT;	2004/07/12 15:05
		((coat\$3 or surfactant or dip or dipped or	US-PGPUB;	
		dipping or immers\$4 or submer\$5 or deposit\$3 or film or layer) with ((wafer	EPO; JPO;	
		or chip or substrate or disc or disk)	DERWENT; IBM TDB	
		near3 (transport\$6)))	12122	
9	924	(427/230,235).CCLS.	USPAT;	2004/07/12 15:05
1.0	010	(407/250 252 254) 0070	US-PGPUB	000440040
10	818	(427/352,353,354).CCLS.	USPAT; US-PGPUB	2004/07/12 15:05
11	3787	(427/372.2,379,384).CCLS.	USPAT;	2004/07/12 15:05
			US-PGPUB	
12	1426	(427/430.1).CCLS.	USPAT;	2004/07/12 15:06
13	777	(438/125).CCLS.	US-PGPUB	2004/07/10 15 06
13	'''	(430/123).CCLS.	USPAT; US-PGPUB	2004/07/12 15:06
14	2995	(206/308.1,524.1,524.6,525,526,832).CCLS.	USPAT;	2004/07/12 15:06
			US-PGPUB	
15	518	(206/524.3).CCLS.	USPAT;	2004/07/12 15:06
16	10837	((427/230,235).CCLS.)	US-PGPUB USPAT;	2004/07/12 15:06
}		((427/352,353,354).CCLS.)	US-PGPUB	2004/07/12 13:00
		((427/372.2,379,384).CCLS.)		
		((427/430.1).CCLS.) ((438/125).CCLS.)		
		((206/308.1,524.1,524.6,525,526,832).CCLS.)		
17	21	((206/524.3).CCLS.) (((427/230,235).CCLS.)	USPAT;	2004/07/12 15:07
		((427/352,353,354).CCLS.)	US-PGPUB	2001,01,12 13.01
		((427/372.2,379,384).CCLS.)		
		((427/430.1).CCLS.) ((438/125).CCLS.)		
		((206/308.1,524.1,524.6,525,526,832).CCLS.)		
		semiconductor) same (surfactant))		
18	0	((206/524.3).CCLS.) and ((wafer or	USPAT;	2004/07/12 15:07
1.0	7.	semiconductor) same (surfactant))	US-PGPUB	
19	76	((((427/230,235).CCLS.) ((427/352,353,354).CCLS.)	USPAT;	2004/07/12 15:08
		((427/372.2,379,384).CCLS.)	US-PGPUB	
	1	((427/430.1).CCLS.) ((438/125).CCLS.)		
	[	((206/308.1,524.1,524.6,525,526,832).CCLS.)		
		((206/524.3).CCLS.)) and ((coat\$3 or surfactant or dip or dipped or dipping or		
		immers\$4 or submer\$5 or deposit\$3 or film		İ
		or layer) with ((wafer or chip or		
		substrate or disc or disk) near3 (storage		
	]	or storing or case or box or holder or	į	
		holding or housing or carrier))) ) and ((prevent\$5 or eliminat\$5 or reduc\$6 or		
1		lower\$3 or stop\$4) near3 (dust\$3 or		
1	1	particle or particulate or contamin\$8))		

20	231	((((427/230,235).CCLS.)	USPAT;	2004/07/12 15:09
20	231	(((427/352,353,354).CCLS.)	US-PGPUB	2004/07/12 15:09
		((427/372.2,379,384).CCLS.)	05 10105	
		((427/430.1).CCLS.) ((438/125).CCLS.)		
		((206/308.1,524.1,524.6,525,526,832).CCLS.)		
		((206/524.3).CCLS.)) and ((coat\$3 or		
		surfactant or dip or dipped or dipping or		
		immers\$4 or submer\$5 or deposit\$3 or film		
		or layer) with ((wafer or chip or		
		substrate or disc or disk) near2 (storage		
		or storing or box or holder or holding or		
		housing or carrier or cartridge))) ) not		
		(((((427/230,235).CCLS.)		
		((427/352,353,354).CCLS.) ((427/372.2,379,384).CCLS.)		
		((427/430.1).CCLS.) ((438/125).CCLS.)		1
		((206/308.1,524.1,524.6,525,526,832).CCLS.)		
		((206/524.3).CCLS.)) and ((coat\$3 or		
		surfactant or dip or dipped or dipping or		
		immers\$4 or submer\$5 or deposit\$3 or film		
		or layer) with ((wafer or chip or		
		substrate or disc or disk) near3 (storage		
		or storing or case or box or holder or		
		holding or housing or carrier))) ) and		
		((prevent\$5 or eliminat\$5 or reduc\$6 or		
		lower\$3 or stop\$4) near3 (dust\$3 or		
21	100	particle or particulate or contamin\$8)))	1100 TD0	0004/07/10 15 11
21	102	((surfactant or scourol) and (((wafer or chip or substrate or disc or disk) near2	EPO; JPO;	2004/07/12 15:11
		(storage or storing or box or holder or	DERWENT; IBM TDB	
		holding or housing or carrier or cartridge	IDM_IDD	
		or case))) ) and (coat\$3 or wash\$3 or		
		clean\$3 or film or layer or deposit\$3 or		
		immers\$5 or submer\$6 or soak\$3 or dip or		
		dipped or dipping)		
22	36	((surfactant or scourol) and (((wafer or	EPO; JPO;	2004/07/12 15:13
		chip or substrate or disc or disk) near2	DERWENT;	
		(storage or storing or box or holder or	IBM_TDB	
		holding or housing or carrier or cartridge		
		or case)))) not (((surfactant or scourol)		
		and (((wafer or chip or substrate or disc		
		or disk) near2 (storage or storing or box or holder or holding or housing or carrier		
		or cartridge or case))) ) and (coat\$3 or		
:		wash\$3 or clean\$3 or film or layer or		
		deposit\$3 or immers\$5 or submer\$6 or		
		soak\$3 or dip or dipped or dipping))		
23	283	((coat\$3 or dip or dipped or dipping or	USPAT;	2004/07/12 15:14
		immers\$4 or submer\$5 or deposit\$3 or film	US-PGPUB	
		or layer or wash\$3 or clean\$3) same		
		((wafer or chip or substrate or disc or		
		disk) near3 (storage or storing or case or		
		box or holder or holding or housing or		
] 24	1 11	carrier))) same (surfactant or scourol)		0004/05/10
24	11	(((coat\$3 or dip or dipped or dipping or immers\$4 or submer\$5 or deposit\$3 or film	USPAT;	2004/07/12 15:15
		or layer) same ((wafer or chip or	US-PGPUB	
		substrate or disc or disk) near3 (storage		
		or storing or case or box or holder or		
İ		holding or housing or carrier))) same		
		(antistatic\$3 or (anti adj static\$3) or		
		((prevent\$4 or eliminat\$3 or reduc\$5 or		
]		stop\$4 or lower\$3) near3 (dust or		
		contamin\$5 or particle or particulate))))		
		and (((427/230,235).CCLS.)		
		((427/352, 353, 354).CCLS.)		
		((427/372.2,379,384).CCLS.)		
		((427/430.1).CCLS.) ((438/125).CCLS.)		
L		((206/308.1,524.1,524.6,525,526,832).CCLS.)		<u></u>
		(\&\U)/J&4.3].\\L\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\		

25	40	((coat\$3 or dip or dipped or dipping or	USPAT;	12004/07/12 15:16
25	40	immers\$4 or submer\$5 or deposit\$3 or film or layer) same ((wafer or chip or	US-PGPUB	2004/07/12 15:16
		substrate or disc or disk) near3 ((storage		
-		or storing or holding or housing or transport\$5) near2 (case or box or holder		
		or carrier)))) same (antistatic\$3 or (anti		
		adj static\$3) or ((prevent\$4 or eliminat\$3		
		or reduc\$5 or stop\$4 or lower\$3) near3 (dust or contamin\$5 or particle or		
		particulate)))		
26	77	(((coat\$3 or dip or dipped or dipping or	USPAT; US-PGPUB	2004/07/12 15:17
		immers\$4 or submer\$5 or deposit\$3 or film or layer) same ((wafer or chip or	US-PGPUB	
		substrate or disc or disk) near3 ((storage		
		or storing or holding or housing or transport\$5) near2 (case or box or holder		
		or carrier)))) and (surfactant)) not		
		((((427/230,235).CCLS.)		
		((427/352,353,354).CCLS.) ((427/372.2,379,384).CCLS.)		
		((427/430.1).CCLS.) ((438/125).CCLS.)		
		((206/308.1,524.1,524.6,525,526,832).CCLS.) ((206/524.3).CCLS.)) and ((coat\$3 or		
		surfactant or dip or dipped or dipping or		
		immers\$4 or submer\$5 or deposit\$3 or film		
		or layer) with ((wafer or chip or substrate or disc or disk) near2 (storage		
		or storing or box or holder or holding or		
27	0	housingaosacarrdep or dappeddge)dipping or	USPAT;	2004/07/12 15:18
		immers\$4 or submer\$5 or deposit\$3 or film or layer) with (surfactant)) ) and	US-PGPUB	
		(((427/230,235).CCLS.)		
		((427/352,353,354).CCLS.) ((427/372.2,379,384).CCLS.)		
		((427/430.1).CCLS.) ((438/125).CCLS.)		
		((206/308.1,524.1,524.6,525,526,832).CCLS.)		
		((206/524.3).CCLS.))) and ((wafer or chip or substrate or disc or disk) near3		
		((storage or storing or holding or housing		
		or transport\$5) near2 (case or box or holder or carrier))))		
28	48	(((wafer or chip or substrate or disc or	USPAT;	2004/07/12 15:19
		disk) near3 (storage or storing or case or	US-PGPUB	
ĺ		<pre>box or holder or holding or housing or carrier or cartridge or transport\$8))) and</pre>		
		((((coat\$3 or dip or dipped or dipping or		
		<pre>immers\$4 or submer\$5 or deposit\$3 or film or layer) with (surfactant)) ) and</pre>		
		(((427/230,235).CCLS.)		
		((427/352,353,354).CCLS.)		
		((427/372.2,379,384).CCLS.) ((427/430.1).CCLS.) ((438/125).CCLS.)		
		((206/308.1,524.1,524.6,525,526,832).CCLS.)		
29	43	((206/524.3).CCLS.))) ((((coat\$3 or dip or dipped or dipping or	HCDAW.	2004/07/12 15 20
29	4.0	immers\$4 or submer\$5 or deposit\$3 or film	USPAT; US-PGPUB	2004/07/12 15:20
		or layer) with (surfactant)) ) and ((wafer		
		or chip or substrate or disc or disk) near3 ((storage or storing or holding or		
		housing or transport\$5) near2 (case or box		
30	156	or holder or carrier))))	IICDAM -	2004/07/10 15 01
] 30	130	immers\$4 or submer\$5 or deposit\$3 or film	USPAT; US-PGPUB	2004/07/12 15:21
		or layer) with (surfactant)) same	-	
		((prevent\$5 or eliminat\$3 or reduc\$5 or stop\$4 or lower\$3) near3 (dust\$3 or		
		contamin\$8))		
				·

31	31	(((coat\$3 or dip or dipped or dipping or	EPO; JPO;	2004/07/12 15:24
		immers\$4 or submer\$5 or deposit\$3 or film	DERWENT;	
		or layer) near5 (surfactant)) ) and	IBM_TDB	
		(((wafer or chip or substrate or disc or		
		disk) near3 (storage or storing or case or		
		box or holder or holding or housing or		
		carrier or cartridge or transport\$8)))		
32	58	((coat\$3 or dip or dipped or dipping or	EPO; JPO;	2004/07/12 15:25
		immers\$4 or submer\$5 or deposit\$3 or film	DERWENT;	
		or layer) near3 (surfactant)) and	IBM TDB	
		((prevent\$5 or eliminat\$3 or reduc\$5 or	_	
1		stop\$4 or lower\$3) near3 (dust\$3 or		
		contamin\$8))		
33	42	(((coat\$3 deposit\$3 or film or layer)	EPO; JPO;	2004/07/12 15:26
		near5 (surfactant)) and (dust\$3 or	DERWENT;	
		contamin\$8) and dry\$3) not (((coat\$3 or	IBM TDB	
		dip or dipped or dipping or immers\$4 or	_	
1		submer\$5 or deposit\$3 or film or layer)		
		near3 (surfactant)) and ((prevent\$5 or	l i	
		eliminat\$3 or reduc\$5 or stop\$4 or		
		<pre>lower\$3) near3 (dust\$3 or contamin\$8)) )</pre>		